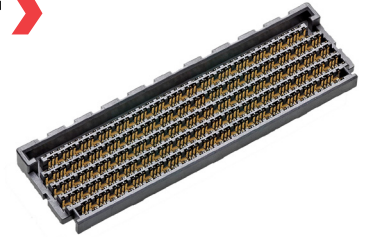


Mirror Mezz 15x11 OCP Connector >

Footprint-compatible, hermaphroditic Mirror Mezz 15x11 OCP Connector lowers application costs with stackable mating that supports data speeds up to 112 Gbps per differential pair, for telecommunications, networking and other applications.

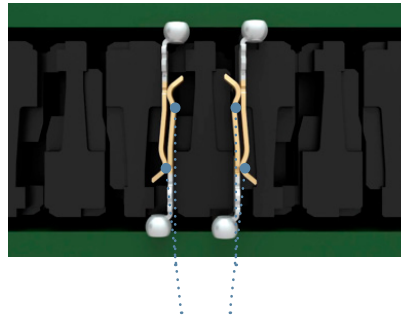
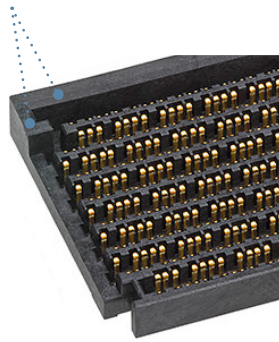


15 x 17 Mirror Mezz OCP Connectors

FEATURES AND ADVANTAGES

Robust shrouded housing design

Encapsulates the pin field, protecting the pins and offering blind-mate guidance to eliminate any possibility of mis-mating

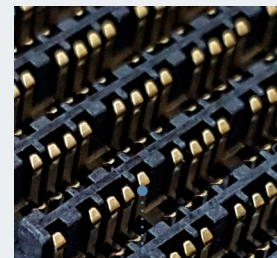
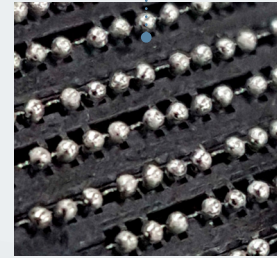


Contact beam structure of a mated combination

Prevents vibrations and terminal lift to ensure a constant 2-points of contact for electrical reliability. Beam geometry offers reliable normal force for harsh environments and 1.50mm of nominal contact wipe to ensure sufficient engagement

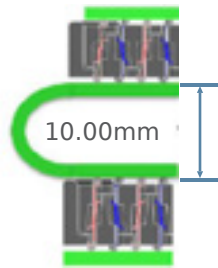
Stitched BGA design

Offers greater cost savings than insert-molded BGA attachments. Stitched contact structure reduces lead times and the connector design simplifies product matrix



Intricate terminal structure design

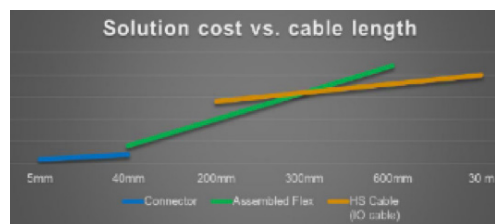
Provides numerous mechanical strengths while also benefiting from cutting-edge electrical features, for some of the fastest speeds in the industry



Using two 5.00mm stack height Mirror Mezz Connectors with 10.00mm flex provides 20.00 to 120.00mm stack heights

Flex cable links

- Offer cost savings and excellent SI with controlled channels and pinned grounds
- Enable relaxed tolerancing for offsets between boards and flexible architectures

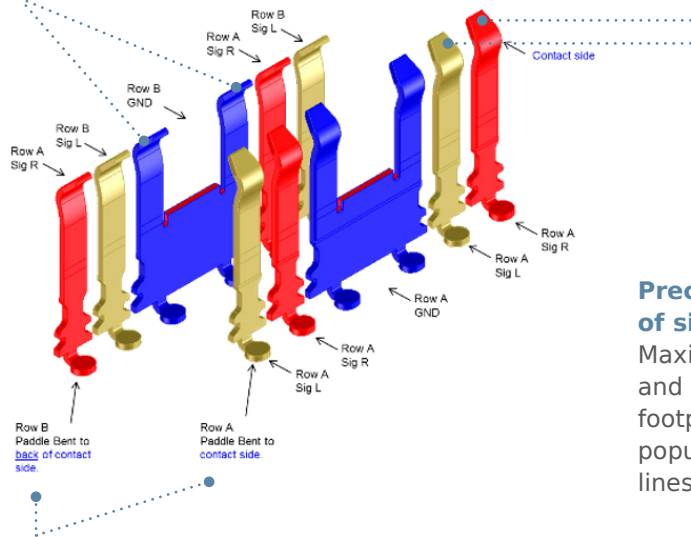


Mirror Mezz 15x11 OCP Connectors >

FEATURES AND ADVANTAGES

Wide ground pins

Balance the electrical field and shield the differential pair from surrounding transmission lines



2 electrically tuned signal contacts

Cleanly transmit high-speed signals for maximum signal integrity surrounding transmission lines

Precise arranged combination of signals and grounds

Maximizes high-speed performance and clean routing out of the connector footprint, with precisely arranged and populated pin fields transmission lines

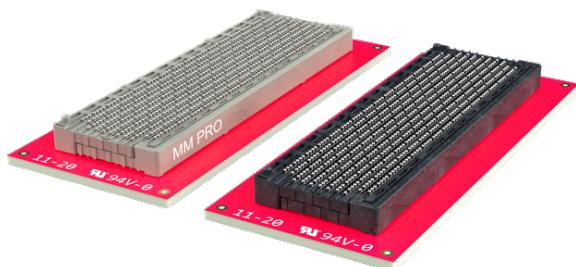
Different paddle-to-contact bend direction between the rows

Minimizes the cross-talk between rows

Mirror Mezz Pro Connectors >

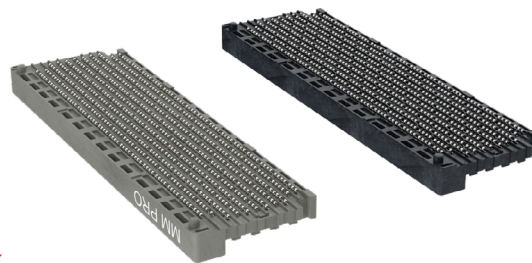
Stitched contacts

Provides lower costs and is more customizable than insert molding



BGA attached and consistent ball profile

Leads to improved and more predictable SI;

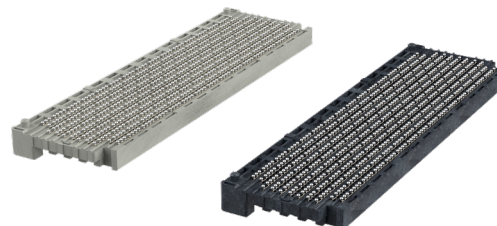


Contact differences between rows; paddles have a bend direction to contact alternates

Minimizes crosstalk between rows (1.50mm-row pitch)

"Stubless" contact interface

Offers superior SI performance with minimum stack height of 5.00mm and two points of contact on every beam for reliability



Mirror Mezz 15x11 OCP Connectors >

MARKETS AND APPLICATIONS

Data/Computing

Servers
Networking
Storage

Telecommunications/Networking

Infrastructure
Networking



Networking

Storage

SPECIFICATION

Reference Information

Packaging: Tape and Reel
Mates With: 2.50 and 5.50mm height
connectors can self- or cross-mate
Designed In: Millimeters
RoHS: Yes
Halogen Free: Yes
Glow Wire Compliant: NA

Electrical

Voltage (max.): 30V AC
Current (max.): 1.0A per contact
Low Level Contact Resistance (max. initial):
0 milliohm for 5mm stack height
Dielectric Withstanding Voltage: 500V DC
Insulation Resistance: 1000 Megohms
Impedance: 90 Ohms

Mechanical

Average Mating Force (max.): 0.35N per pin
Unmating Force (min.): 0.045N per pin
Contact Normal Force (min.): 0.2N per pin
Durability (max.): 100 cycles

Physical

Housing: High Temperature
Thermoplastic, UL94-V0
Contact: High Performance Copper Alloy
Plating: Selective Gold
Contact Area — 0.76 micron Gold (Au)
Solder Tail Area — 2.54 micron Tin (Sn)
Underplating — 1.27 micron Nickel (Ni)
Operating Temperature: -55 to +105°C

www.molex.com/link/mirrormezz.html